KVR1066D3N7K3/3G

3GB (1GB 1Rx8 128M x 64-Bit x 3 pcs.)
PC3-8500 CL7 240-Pin DIMM Kit

Important Information: The module defined in this data sheet is one of several configurations available under this part number. While all configurations are compatible, the DRAM combination and/or the module height may vary from what is described here.

DESCRIPTION

ValueRAM's KVR1066D3N7K3/3G is a kit of three 128M x 64-bit (1GB) DDR3-1066 CL7 SDRAM (Synchronous DRAM), 1Rx8 memory modules, based on eight 128M x 8-bit DDR3-1066 FBGA components per module. Total kit capacity is 3GB. The SPD's are programmed to JEDEC standard latency DDR3-1066 timing of 7-7-7 at 1.5V. Each 240-pin DIMM uses gold contact fingers. The electrical and mechanical specifications are as follows:

FEATURES

- JEDEC standard 1.5V (1.425V ~1.575V) Power Supply
- VDDQ = 1.5V (1.425V ~ 1.575V)
- 533MHz fCK for 1066Mb/sec/pin
- 8 independent internal bank
- Programmable CAS Latency: 8, 7, 6
- Programmable Additive Latency: 0, CL - 2, or CL - 1 clock
- Programmable CAS Write Latency(CWL) = 6 (DDR3-1066)
- 8-bit pre-fetch
- Burst Length: 8 (Interleave without any limit, sequential with starting address “000” only), 4 with tCCD = 4 which does not allow seamless read or write [either on the fly using A12 or MRS]
- Bi-directional Differential Data Strobe
- Internal(self) calibration: Internal self calibration through ZQ pin (RZQ : 240 ohm ± 1%)
- On Die Termination using ODT pin
- Average Refresh Period 7.8us at lower than TCASE 85°C, 3.9us at 85°C < TCASE ≤ 95°C
- Asynchronous Reset
- PCB: Height 0.740” (18.75mm), single sided component

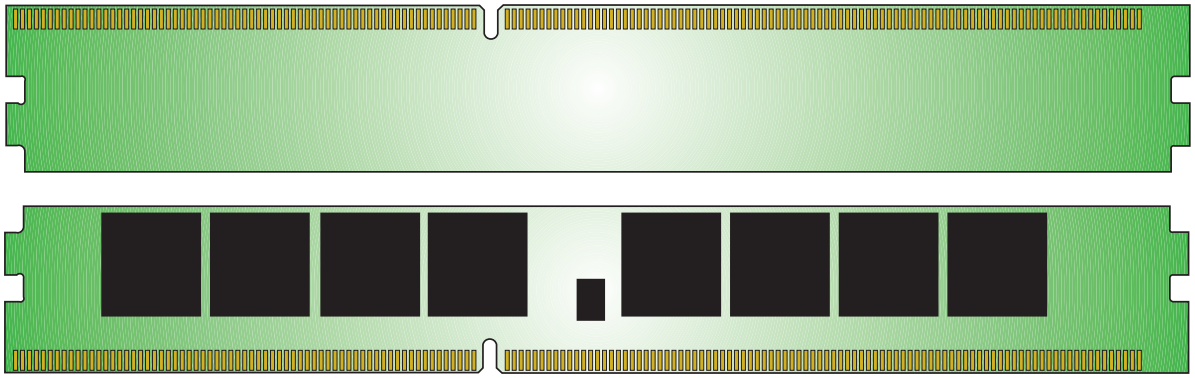
SPECIFICATIONS

CL(IDD)	7 cycles
Row Cycle Time (tRCmin)	50.63ns (min.)
Refresh to Active/Refresh Command Time (tRFCmin)	110ns (min.)
Row Active Time (tRASmin)	37.5ns (min.)
Power (Operating)	1.080 W* (per module)
UL Rating	94 V - 0
Operating Temperature	0° C to 85° C
Storage Temperature	-55° C to +100° C

*Power will vary depending on the SDRAM used.

Continued >>

MODULE DIMENSIONS:



Units = Millimeters

